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IN THE UNITED STATES PATENT OFFICE

GPO 19500

Inventors: F. Kish, et al. Serial No.: 08/298,691
Filed: August 31, 1994 Examiner: W. Mintel
Art Unit: 2503
For: Wafer Bonding of Light Emitting Diode Layers

AMENDMENT

Honorable Assistant Commissioner of
Patents
Washington, D.C. 20231

NOT ENTERED

Dear Sir:

In response to the Office Action of 13 June 1995, applicant requests that the following changes to the claims be made.

In The Claims:

Please amend claim 14 as indicated below.

14 (Twice Amended). A light emitting semiconductor device comprising:

an arrangement of semiconductor layers for generating light in response to a conduction of current;

an optically transparent wafer-bond layer coupled to said semiconductor layers, an interface of said wafer-bond layer with the semiconductor layers exhibiting properties characteristic of layers that have undergone wafer bonding, including a conductive ohmic bond to said semiconductor layers and being mechanically robust; and

electrode means for applying a current to said arrangement of semiconductor layers.

Cancel claim 18, without prejudice.